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Electromagnetic compatibility (EMC) –

Part 4-33:
Testing and measurement techniques – Measurement methods for high-power transient parameters

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-33: Testing and measurement techniques – Measurement methods for high-power transient parameters

FOREWORD

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International Standard IEC 61000-4-33 has been prepared by subcommittee 77C: High power transient phenomena, of IEC technical committee 77: Electromagnetic compatibility.

It has the status of a basic EMC publication in accordance with IEC Guide 107.

The text of this standard is based on the following documents:

FDIS	Report on voting
77C/156/FDIS	77C/160/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

INTRODUCTION

IEC 61000 is published in separate parts according to the following structure:

Part 1: General

General considerations (introduction, fundamental principles)

Definitions, terminology

Part 2: Environment

Description of the environment

Classification of the environment

Compatibility levels

Part 3: Limits

Emission limits

Immunity limits (in so far as they do not fall under the responsibility of the product committees)

Part 4: Testing and measurement techniques

Measurement techniques

Testing techniques

Part 5: Installation and mitigation guidelines

Installation guidelines

Mitigation methods and devices

Part 6: Generic standards

Part 9: Miscellaneous

Each part is further subdivided into several parts and published either as International Standards or as technical specifications or technical reports, some of which have already been published as sections. Others will be published with the part number followed by a dash and a second number identifying the subdivision (example: 61000-6-1).

ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-33: Testing and measurement techniques – Measurement methods for high-power transient parameters

1 Scope

This part of IEC 61000 provides a basic description of the methods and means (e.g., instrumentation) for measuring responses arising from high-power transient electromagnetic parameters. These responses can include:

– the electric (*E*) and/or magnetic (*H*) fields (e.g., incident fields or incident plus scattered fields within a system under test);

– the current *I* (e.g., induced by a transient field or within a system under test);

– the voltage *V* (e.g., induced by a transient field or within a system under test);

– the charge *Q* induced on a cable or other conductor.

NOTE The charge *Q* on the conductor is a fundamental quantity that can be defined at any frequency. The voltage *V*, however, is a defined (e.g., secondary) quantity, which is valid only at low frequencies. At high frequencies, the voltage cannot be defined as the line integral of the E-field, since this integral is path-dependent. Thus, for very fast rising pulses (having a large high-frequency spectral content) the use of the voltage as a measurement observable is not valid. In this case, the charge is the desired quantity to be measured.

These measured quantities are generally complicated time-dependent waveforms, which can be described approximately by several scalar parameters, or "observables". These parameters include:

– the peak amplitude of the response,

– the waveform rise-time,

– the waveform fall-time (or duration),

– the pulse width, and

– mathematically defined norms obtained from the waveform.

This International Standard provides information on the measurement of these waveforms and on the mathematical determination of the characterizing parameters. It does not provide information on specific level requirements for testing.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-161, *International Electrotechnical Vocabulary (IEV) – Chapter 161: Electromagnetic compatibility*

IEC 61000-2-9, *Electromagnetic compatibility (EMC) – Part 2: Environment – Section 9: Description of HEMP environment – Radiated disturbance*

IEC 61000-2-10, *Electromagnetic compatibility (EMC) – Part 2-10: Environment – Description of HEMP environment – Conducted disturbance*

IEC 61000-4-20, *Electromagnetic compatibility (EMC) – Part 4-20: Testing and measurement techniques – Emission and immunity testing in transverse electromagnetic (TEM) waveguides*

IEC 61000-4-23, *Electromagnetic compatibility (EMC) – Part 4-23: Testing and measurement techniques – Test methods for protective devices for HPEM and other radiated disturbances*

IEC 61000-4-25, *Electromagnetic compatibility (EMC) – Part 4-25: Testing and measurement techniques – HEMP immunity test methods for equipment and systems*